



- ⦿ AEC-Q200 Compliant
- ⦿ Designed for use with ADI LTC6804/681X series, NXP MC33771/33772 and TI BQ79616
- ⦿ Design Construction: Basic insulation per IEC 60664-1
- ⦿ Creepage Distance:  $\geq 10\text{mm}$ , per pollution 2 & material group 1
- ⦿ Operating Temperature:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- ⦿ Storage Temperature:  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- ⦿ Lead Finish: Sn100
- ⦿ Moisture Sensitivity Level: 1

## Electrical Specifications @ 25°C

Part Number	Turns Ratio ( $\pm 5\%$ )	Inductance 100kHz, 0.1 Vrms ( $\mu\text{H}$ )		Insertion Loss (dB MAX)	Return Loss (dB MIN)	Dielectric Withstanding Voltage 60S MIN (VDC)
	$\frac{(1-3)}{(6-4)}$	MIN	MAX	4 MHz	4 MHz	
RA1059NL	1CT:1CT	150	450	0.30	20	(1-3) to (6-4)

### NOTES:

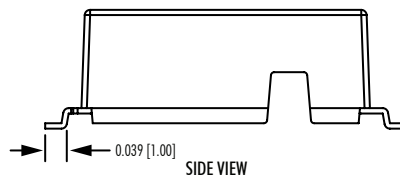
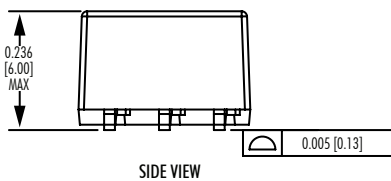
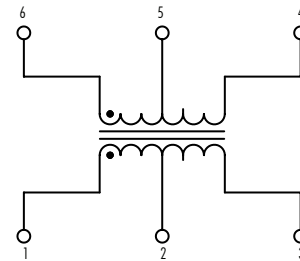
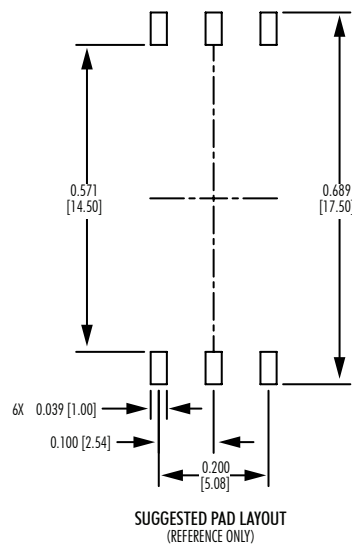
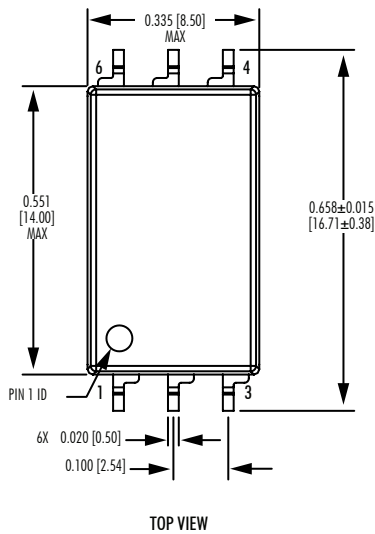
1. For Tape & Reel packaging, add "T" suffix at the end of the part number: i.e. RA1059NLT

### Mechanicals

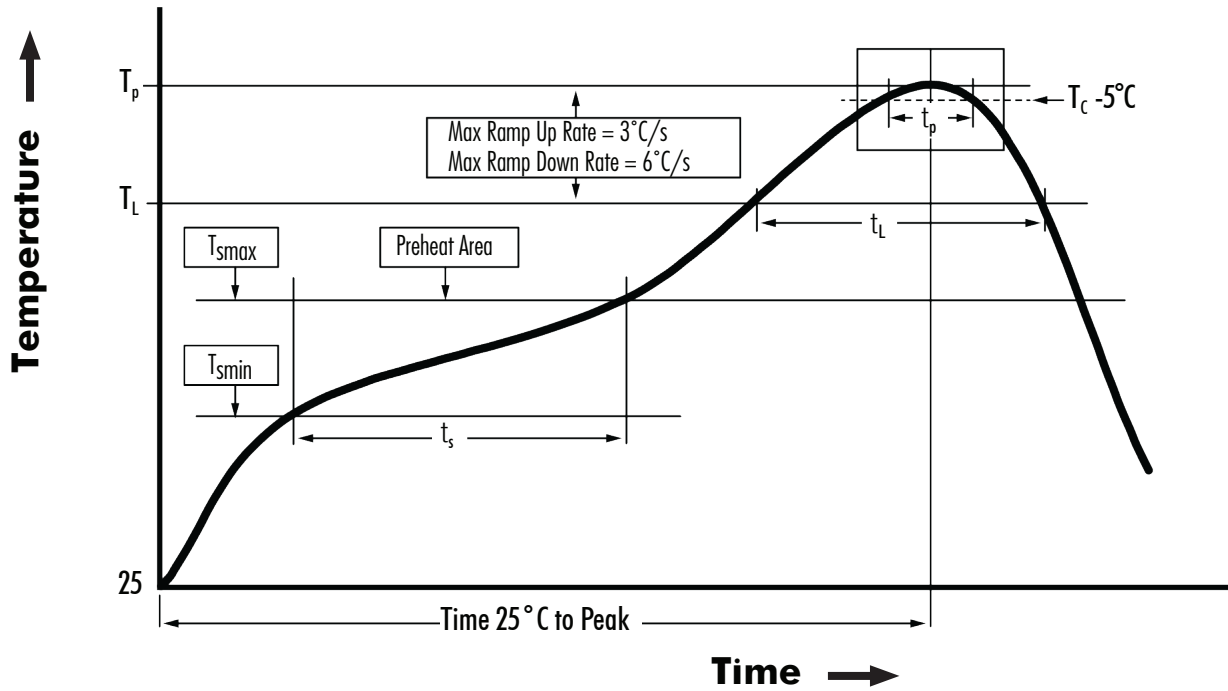
### Electrical Schematics

RA1059NL

Dimensions: inch [mm]  
Tolerance (unless otherwise specified):  $\pm 0.010$  [0.25]



## Non-Lead Recommended Reflow Profile (Based on J-STD-020D)



$T_{SMIN}$ (°C)	$T_{SMAX}$ (°C)	$T_L$ (°C)	$T_P$ (°C MAX)	$t_s$ (s)	$t_L$ (s)	$t_p$ (s MAX)	Ramp-up rate ( $T_L$ to $T_P$ )	Ramp-down rate ( $T_P$ to $T_L$ )	Time 25°C to peak temperature (s MAX)
150	200	217	245	60 - 120	60 - 150	30	3°C/s MAX	6°C/s MAX	480

**NOTES:**

1. All temperatures measured on the package leads.
2. Maximum number of reflow cycles not to exceed 2.

